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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2400
Number of Logic Elements/Cells	10800
Total RAM Bits	163840
Number of I/O	404
Number of Gates	569952
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	560-LBGA Exposed Pad, Metal
Supplier Device Package	560-MBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv400e-6bg560i

resources. The abundance of routing resources permits the Virtex-E family to accommodate even the largest and most complex designs.

Virtex-E FPGAs are SRAM-based, and are customized by loading configuration data into internal memory cells. Configuration data can be read from an external SPROM (master serial mode), or can be written into the FPGA (SelectMAP™, slave serial, and JTAG modes).

The standard Xilinx Foundation Series™ and Alliance Series™ Development systems deliver complete design support for Virtex-E, covering every aspect from behavioral and schematic entry, through simulation, automatic design translation and implementation, to the creation and downloading of a configuration bit stream.

Higher Performance

Virtex-E devices provide better performance than previous generations of FPGAs. Designs can achieve synchronous system clock rates up to 240 MHz including I/O or 622 Mb/s using Source Synchronous data transmission architectures. Virtex-E I/Os comply fully with 3.3 V PCI specifications, and interfaces can be implemented that operate at 33 MHz or 66 MHz.

While performance is design-dependent, many designs operate internally at speeds in excess of 133 MHz and can achieve over 311 MHz. Table 2 shows performance data for representative circuits, using worst-case timing parameters.

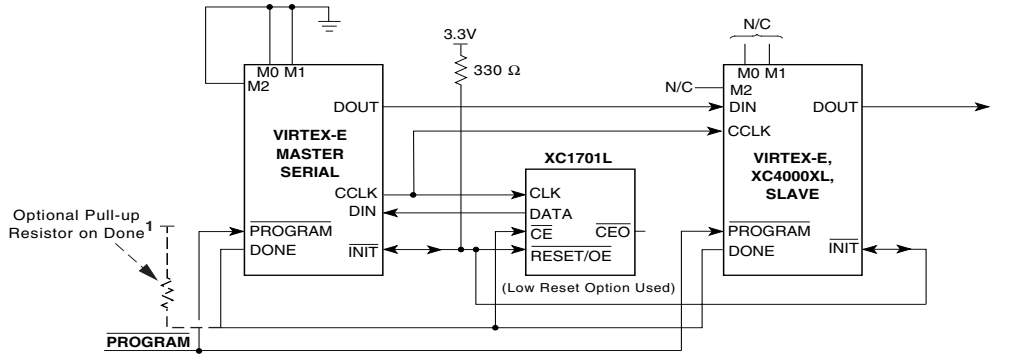
Table 2: **Performance for Common Circuit Functions**

Function	Bits	Virtex-E (-7)
Register-to-Register		
Adder	16 64	4.3 ns 6.3 ns
Pipelined Multiplier	8 x 8 16 x 16	4.4 ns 5.1 ns
Address Decoder	16 64	3.8 ns 5.5 ns
16:1 Multiplexer		4.6 ns
Parity Tree	9 18 36	3.5 ns 4.3 ns 5.9 ns
Chip-to-Chip		
HSTL Class IV		
LVTTL,16mA, fast slew		
LVDS		
LVPECL		

Virtex-E Device/Package Combinations and Maximum I/O

Table 3: **Virtex-E Family Maximum User I/O by Device/Package (Excluding Dedicated Clock Pins)**

	XCV 50E	XCV 100E	XCV 200E	XCV 300E	XCV 400E	XCV 600E	XCV 1000E	XCV 1600E	XCV 2000E	XCV 2600E	XCV 3200E
CS144	94	94	94								
PQ240	158	158	158	158	158						
HQ240						158	158				
BG352		196	260	260							
BG432				316	316	316					
BG560					404	404	404	404	404		
FG256	176	176	176	176							
FG456			284	312							
FG676					404	444					
FG680						512	512	512	512		
FG860							660	660	660		
FG900						512	660	700			
FG1156							660	724	804	804	804



Note 1: If none of the Virtex FPGAs have been selected to drive DONE, an external pull-up resistor of 330 Ω should be added to the common DONE line. (For Spartan-XL devices, add a 4.7K Ω pull-up resistor.) This pull-up is not needed if the DriveDONE attribute is set. If used, DriveDONE should be selected only for the last device in the configuration chain.

XCVE_ds_013_050103

Figure 13: **Master/Slave Serial Mode Circuit Diagram**

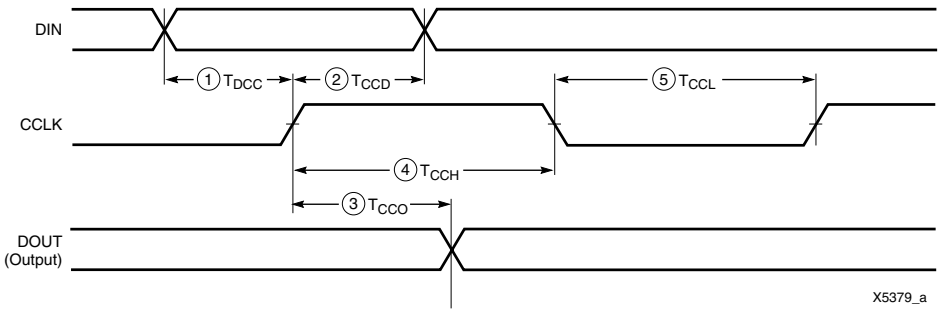


Figure 14: **Slave-Serial Mode Programming Switching Characteristics**

Master-Serial Mode

In master-serial mode, the CCLK output of the FPGA drives a Xilinx Serial PROM that feeds bit-serial data to the DIN input. The FPGA accepts this data on each rising CCLK edge. After the FPGA has been loaded, the data for the next device in a daisy-chain is presented on the DOUT pin after the rising CCLK edge. The maximum capacity for a single LOUT/DOUT write is 2^{20}-1 (1,048,575) 32-bit words, or 33,554,4000 bits.

The interface is identical to slave-serial except that an internal oscillator is used to generate the configuration clock (CCLK). A wide range of frequencies can be selected for CCLK, which always starts at a slow default frequency. Configuration bits then switch CCLK to a higher frequency for the remainder of the configuration. Switching to a lower frequency is prohibited.

The CCLK frequency is set using the ConfigRate option in the bitstream generation software. The maximum CCLK frequency that can be selected is 60 MHz. When selecting a CCLK frequency, ensure that the serial PROM and any daisy-chained FPGAs are fast enough to support the clock rate.

On power-up, the CCLK frequency is approximately 2.5 MHz. This frequency is used until the ConfigRate bits have been loaded when the frequency changes to the selected ConfigRate. Unless a different frequency is specified in the design, the default ConfigRate is 4 MHz.

In a full master/slave system (Figure 13), the left-most device operates in master-serial mode. The remaining devices operate in slave-serial mode. The SPROM $\overline{\text{RESET}}$ pin is driven by $\overline{\text{INIT}}$, and the $\overline{\text{CE}}$ input is driven by DONE. There is the potential for contention on the DONE pin, depending on the start-up sequence options chosen.

The sequence of operations necessary to configure a Virtex-E FPGA serially appears in Figure 15.

Data Output Bus—DO[A|B]<#:0>

The data out bus reflects the contents of the memory cells referenced by the address bus at the last active clock edge. During a write operation, the data out bus reflects the data in bus. The width of this bus equals the width of the port. The allowed widths appear in Table 15.

Inverting Control Pins

The four control pins (CLK, EN, WE and RST) for each port have independent inversion control as a configuration option.

Address Mapping

Each port accesses the same set of 4096 memory cells using an addressing scheme dependent on the width of the port.

The physical RAM location addressed for a particular width are described in the following formula (of interest only when the two ports use different aspect ratios).

$$Start = ((ADDR_{port} + 1) * Width_{port}) - 1$$

$$End = ADDR_{port} * Width_{port}$$

Conflict Resolution

The block SelectRAM+ memory is a true dual-read/write port RAM that allows simultaneous access of the same memory cell from both ports. When one port writes to a given memory cell, the other port must not address that memory cell (for a write or a read) within the clock-to-clock setup window. The following lists specifics of port and memory cell write conflict resolution.

- If both ports write to the same memory cell simultaneously, violating the clock-to-clock setup requirement, consider the data stored as invalid.
- If one port attempts a read of the same memory cell the other simultaneously writes, violating the clock-to-clock setup requirement, the following occurs.
  - The write succeeds
  - The data out on the writing port accurately reflects the data written.
  - The data out on the reading port is invalid.

Conflicts do not cause any physical damage.

Table 16 shows low order address mapping for each port width.

Table 16: **Port Address Mapping**

Port Width	Port Addresses																
1	4095...	15	14	13	12	11	10	09	08	07	06	05	04	03	02	01	00
2	2047...	07		06		05		04		03		02		01		00	
4	1023...	03				02				01				00			
8	511...	01								00							
16	255...	00															

Creating Larger RAM Structures

The block SelectRAM+ columns have specialized routing to allow cascading blocks together with minimal routing delays. This achieves wider or deeper RAM structures with a smaller timing penalty than when using normal routing channels.

Location Constraints

Block SelectRAM+ instances can have LOC properties attached to them to constrain the placement. The block SelectRAM+ placement locations are separate from the CLB location naming convention, allowing the LOC properties to transfer easily from array to array.

The LOC properties use the following form.

LOC = RAMB4_R#C#

RAMB4_R0C0 is the upper left RAMB4 location on the device.

Single Port Timing

Figure 33 shows a timing diagram for a single port of a block SelectRAM+ memory. The block SelectRAM+ AC switching characteristics are specified in the data sheet. The block SelectRAM+ memory is initially disabled.

At the first rising edge of the CLK pin, the ADDR, DI, EN, WE, and RST pins are sampled. The EN pin is High and the WE pin is Low indicating a read operation. The DO bus contains the contents of the memory location, 0x00, as indicated by the ADDR bus.

At the second rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN and WE pins are High indicating a write operation. The DO bus mirrors the DI bus. The DI bus is written to the memory location 0x0F.

At the third rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN pin is High and the WE pin is Low indicating a read operation. The DO bus contains the contents of the memory location 0x7E as indicated by the ADDR bus.

At the fourth rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN pin is Low

VHDL Initialization Example

```
library IEEE;
use IEEE.std_logic_1164.all;

entity MYMEM is
port (CLK, WE:in std_logic;
ADDR: in std_logic_vector(8 downto 0);
DIN: in std_logic_vector(7 downto 0);
DOUT: out std_logic_vector(7 downto 0));
end MYMEM;

architecture BEHAVE of MYMEM is
signal logic0, logic1: std_logic;

component RAMB4_S8
--synopsys translate_off
generic( INIT_00,INIT_01, INIT_02, INIT_03, INIT_04, INIT_05, INIT_06, INIT_07,
INIT_08, INIT_09, INIT_0a, INIT_0b, INIT_0c, INIT_0d, INIT_0e, INIT_0f : BIT_VECTOR(255
downto 0)
:= X"0000000000000000000000000000000000000000000000000000000000000000");
--synopsys translate_on
port (WE, EN, RST, CLK: in STD_LOGIC;
ADDR: in STD_LOGIC_VECTOR(8 downto 0);
DI: in STD_LOGIC_VECTOR(7 downto 0);
DO: out STD_LOGIC_VECTOR(7 downto 0));
end component;

--synopsys dc_script_begin
--set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
--set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
--synopsys dc_script_end

begin
logic0 <='0';
logic1 <='1';

ram0: RAMB4_S8
--synopsys translate_off
generic map (

INIT_00 => X"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF",
INIT_01 => X"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210")
--synopsys translate_on
port map (WE=>WE, EN=>logic1, RST=>logic0, CLK=>CLK,ADDR=>ADDR, DI=>DIN, DO=>DOUT);

end BEHAVE;
```

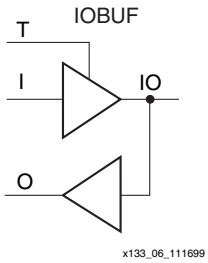


Figure 42: **Input/Output Buffer Symbol (IOBUF)**

The following list details variations of the IOBUF symbol.

- IOBUF
- IOBUF_S_2
- IOBUF_S_4
- IOBUF_S_6
- IOBUF_S_8
- IOBUF_S_12
- IOBUF_S_16
- IOBUF_S_24
- IOBUF_F_2
- IOBUF_F_4
- IOBUF_F_6
- IOBUF_F_8
- IOBUF_F_12
- IOBUF_F_16
- IOBUF_F_24
- IOBUF_LVCMOS2
- IOBUF_PCI33_3
- IOBUF_PCI66_3
- IOBUF_GTL
- IOBUF_GTLP
- IOBUF_HSTL_I
- IOBUF_HSTL_III
- IOBUF_HSTL_IV
- IOBUF_SSTL3_I
- IOBUF_SSTL3_II
- IOBUF_SSTL2_I
- IOBUF_SSTL2_II
- IOBUF_CTT
- IOBUF_AGP
- IOBUF_LVCMOS18
- IOBUF_LVDS
- IOBUF_LVPECL

When the IOBUF symbol used supports an I/O standard that requires a differential amplifier input, the IOBUF automatically configures with a differential amplifier input buffer.

The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}.

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38, page 34 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IOBUF placement restrictions require any differential amplifier input signals within a bank be of the same standard.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Additional restrictions on the Virtex-E SelectI/O IOBUF placement require that within a given V_{CCO} bank each IOBUF must share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within the same V_{CCO} bank. The LOC property can specify a location for the IOBUF.

An optional delay element is associated with the input path in each IOBUF. When the IOBUF drives an input flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Override this default with the NODELAY=TRUE property.

In the case when the IOBUF does not drive an input flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

3-state output buffers and bidirectional buffers can have either a weak pull-up resistor, a weak pull-down resistor, or a weak “keeper” circuit. Control this feature by adding the appropriate symbol to the output net of the IOBUF (PULLUP, PULLDOWN, or KEEPER).

SelectI/O Properties

Access to some of the SelectI/O features (for example, location constraints, input delay, output drive strength, and slew rate) is available through properties associated with these features.

Input Delay Properties

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Use the NODELAY=TRUE property to override this default.

In the case when the IBUF does not drive a flip-flop within the IOB, the delay element by default de-activates to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

HSTL

A sample circuit illustrating a valid termination technique for HSTL_I appears in Figure 46. A sample circuit illustrating a valid termination technique for HSTL_III appears in Figure 47.

Table 25: **HSTL Class I Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	0.68	0.75	0.90
V_{TT}	-	$V_{CCO} \times 0.5$	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}			0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

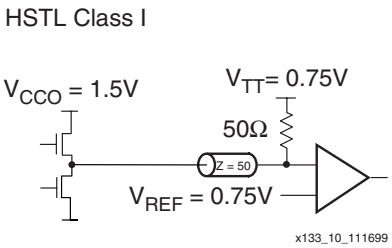


Figure 46: **Terminated HSTL Class I**

Table 26: **HSTL Class III Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF} (1)	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	24	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user."

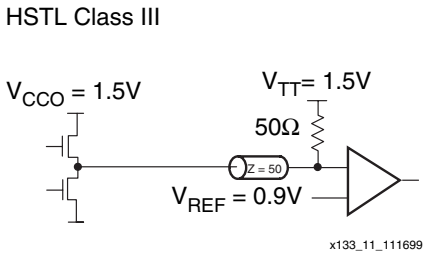


Figure 47: **Terminated HSTL Class III**

A sample circuit illustrating a valid termination technique for HSTL_IV appears in Figure 48.

Table 27: **HSTL Class IV Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	48	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user.

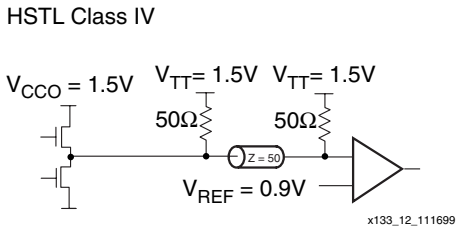


Figure 48: **Terminated HSTL Class IV**

SSTL2_II

A sample circuit illustrating a valid termination technique for SSTL2_II appears in Figure 52. DC voltage specifications appear in Table 31.

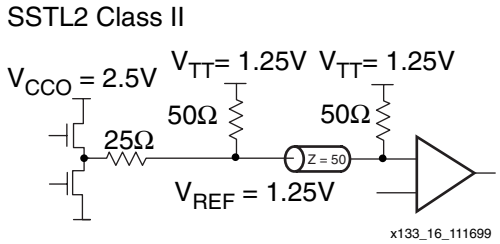


Figure 52: **Terminated SSTL2 Class II**

Table 31: **SSTL2_II Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
$V_{REF} = 0.5 \times V_{CCO}$	1.15	1.25	1.35
$V_{TT} = V_{REF} + N$(1)	1.11	1.25	1.39
$V_{IH} = V_{REF} + 0.18$	1.33	1.43	3.0(2)
$V_{IL} = V_{REF} - 0.18$	–0.3(3)	1.07	1.17
$V_{OH} = V_{REF} + 0.8$	1.95	-	-
$V_{OL} = V_{REF} - 0.8$	-	-	0.55
I_{OH} at V_{OH} (mA)	–15.2	-	-
I_{OL} at V_{OL} (mA)	15.2	-	-

Notes:
1. N must be greater than or equal to -0.04 and less than or equal to 0.04.
2. V_{IH} maximum is V_{CCO} + 0.3.
3. V_{IL} minimum does not conform to the formula.

CTT

A sample circuit illustrating a valid termination technique for CTT appear in Figure 53. DC voltage specifications appear in Table 32.

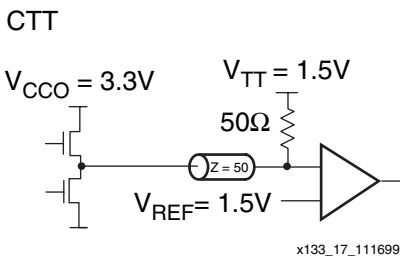


Figure 53: **Terminated CTT**

Table 32: **CTT Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.05(1)	3.3	3.6
V_{REF}	1.35	1.5	1.65
V_{TT}	1.35	1.5	1.65
$V_{IH} = V_{REF} + 0.2$	1.55	1.7	-
$V_{IL} = V_{REF} - 0.2$	-	1.3	1.45
$V_{OH} = V_{REF} + 0.4$	1.75	1.9	-
$V_{OL}= V_{REF} - 0.4$	-	1.1	1.25
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

Notes:
1. Timing delays are calculated based on V_{CCO} min of 3.0V.

PCI33_3 & PCI66_3

PCI33_3 or PCI66_3 require no termination. DC voltage specifications appear in Table 33.

Table 33: **PCI33_3 and PCI66_3 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
$V_{IH} = 0.5 \times V_{CCO}$	1.5	1.65	V_{CCO} + 0.5
$V_{IL} = 0.3 \times V_{CCO}$	–0.5	0.99	1.08
$V_{OH} = 0.9 \times V_{CCO}$	2.7	-	-
$V_{OL}= 0.1 \times V_{CCO}$	-	-	0.36
I_{OH} at V_{OH} (mA)	Note 1	-	-
I_{OL} at V_{OL} (mA)	Note 1	-	-

Notes:
1. Tested according to the relevant specification.

LVDS

Depending on whether the device is transmitting an LVDS signal or receiving an LVDS signal, there are two different circuits used for LVDS termination. A sample circuit illustrating a valid termination technique for transmitting LVDS signals appears in Figure 54. A sample circuit illustrating a valid termination for receiving LVDS signals appears in Figure 55. Table 38 lists DC voltage specifications. Further information on the specific termination resistor packs shown can be found on Table 40.

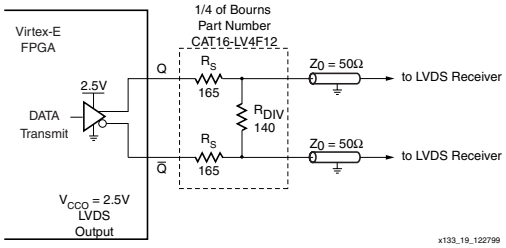


Figure 54: **Transmitting LVDS Signal Circuit**

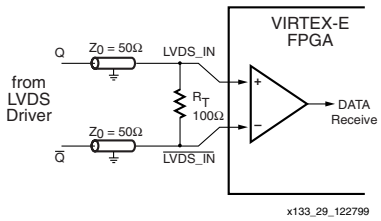


Figure 55: **Receiving LVDS Signal Circuit**

Table 38: **LVDS Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.375	2.5	2.625
V_{ICM}(2)	0.2	1.25	2.2
V_{OCM}(1)	1.125	1.25	1.375
V_{IDIFF} (1)	0.1	0.35	-
V_{ODIFF} (1)	0.25	0.35	0.45
V_{OH}(1)	1.25	-	-
V_{OL}(1)	-	-	1.25

Notes:
1. Measured with a 100 Ω resistor across Q and $\overline{Q}$.
2. Measured with a differential input voltage = +/– 350 mV.

LVPECL

Depending on whether the device is transmitting or receiving an LVPECL signal, two different circuits are used for LVPECL termination. A sample circuit illustrating a valid termination technique for transmitting LVPECL signals appears in Figure 56. A sample circuit illustrating a valid termination for receiving LVPECL signals appears in Figure 57. Table 39 lists DC voltage specifications. Further information on the specific termination resistor packs shown can be found on Table 40.

Table 39: **LVPECL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	1.49	-	2.72
V_{IL}	0.86	-	2.125
V_{OH}	1.8	-	-
V_{OL}	-	-	1.57

Notes:
1. For more detailed information, see **DS022-3**: *Virtex-E 1.8V FPGA DC and Switching Characteristics*, Module 3, LVPECL DC Specifications section.

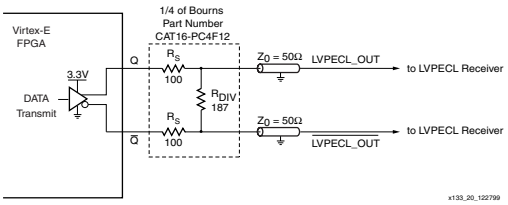


Figure 56: **Transmitting LVPECL Signal Circuit**

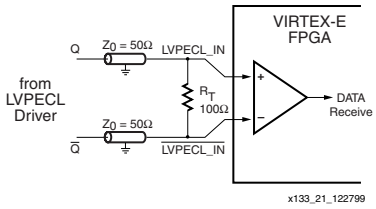


Figure 57: **Receiving LVPECL Signal Circuit**

CS144 Chip-Scale Package

XCV50E, XCV100E, XCV200E, XCV300E and XCV400E devices in CS144 Chip-scale packages have footprint compatibility. In the CS144 package, bank pairs that share a side are internally interconnected, permitting four choices for V_{CCO}. See Table 3.

Table 3: **I/O Bank Pairs and Shared Vcco Pins**

Paired Banks	Shared V_{CCO} Pins
Banks 0 & 1	A2, A13, D7
Banks 2 & 3	B12, G11, M13
Banks 4 & 5	N1, N7, N13
Banks 6 & 7	B2, G2, M2

Pins labeled I0_VREF can be used as either in all parts unless device-dependent, as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 4, see Table 5 is Differential Pair information.

Table 4: **CS144 — XCV50E, XCV100E, XCV200E**

Bank	Pin Description	Pin #
0	GCK3	A6
0	IO	B3
0	IO_VREF_L0N_YY	B4[2]
0	IO_L0P_YY	A4
0	IO_L1N_YY	B5
0	IO_L1P_YY	A5
0	IO_LVDS_DLL_L2N	C6
0	IO_VREF	A3[1]
0	IO_VREF	C4
0	IO_VREF	D6
1	GCK2	A7
1	IO	A8
1	IO_LVDS_DLL_L2P	B7
1	IO_L3N_YY	C8
1	IO_L3P_YY	D8
1	IO_L4N_YY	C9
1	IO_VREF_L4P_YY	D9[2]
1	IO_WRITE_L5N_YY	C10
1	IO_CS_L5P_YY	D10
1	IO_VREF	A10
1	IO_VREF	B8
1	IO_VREF	B10[1]
2	IO	D12
2	IO	F12
2	IO_DOUT_BUSY_L6P_YY	C11
2	IO_DIN_D0_L6N_YY	C12
2	IO_D1_L7N	E10
2	IO_VREF_L7P	D13[2]
2	IO_L8N_YY	E13
2	IO_D2_L8P_YY	E12
2	IO_D3_L9N	F11
2	IO_VREF_L9P	F10
2	IO_L10P	F13
2	IO_VREF	C13[1]
2	IO_VREF	D11
3	IO	H13
3	IO	K13
3	IO_L10N	G13
3	IO_VREF_L11N	H11
3	IO_D4_L11P	H12
3	IO_D5_L12N_YY	J13
3	IO_L12P_YY	H10
3	IO_VREF_L13N	J10[2]
3	IO_D6_L13P	J11
3	IO_INIT_L14N_YY	L13
3	IO_D7_L14P_YY	K10
3	IO_VREF	K11[1]
3	IO_VREF	K12
4	GCK0	K7
4	IO	M8
4	IO	M10

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P137	VCCINT	NA
P104	VCCINT	NA
P88	VCCINT	NA
P77	VCCINT	NA
P43	VCCINT	NA
P32	VCCINT	NA
P16	VCCINT	NA
P240	VCCO	7
P232	VCCO	0
P226	VCCO	0
P212	VCCO	0
P207	VCCO	1
P197	VCCO	1
P180	VCCO	1
P176	VCCO	2
P165	VCCO	2
P150	VCCO	2
P146	VCCO	3
P136	VCCO	3
P121	VCCO	3
P116	VCCO	4
P105	VCCO	4
P90	VCCO	4
P85	VCCO	5
P76	VCCO	5
P61	VCCO	5
P55	VCCO	6
P44	VCCO	6
P30	VCCO	6
P25	VCCO	7
P15	VCCO	7
P233	GND	NA
P227	GND	NA

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P219	GND	NA
P211	GND	NA
P204	GND	NA
P196	GND	NA
P190	GND	NA
P182	GND	NA
P172	GND	NA
P166	GND	NA
P158	GND	NA
P151	GND	NA
P143	GND	NA
P135	GND	NA
P129	GND	NA
P119	GND	NA
P112	GND	NA
P106	GND	NA
P98	GND	NA
P91	GND	NA
P83	GND	NA
P75	GND	NA
P69	GND	NA
P59	GND	NA
P51	GND	NA
P45	GND	NA
P37	GND	NA
P29	GND	NA
P22	GND	NA
P14	GND	NA
P8	GND	NA
P1	GND	NA

Notes:

1. V_{REF} or I/O option only in the XCV100E, 200E, 300E, 400E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV200E, 300E, 400E; otherwise, I/O option only.
3. V_{REF} or I/O option only in the XCV400E; otherwise, I/O option only.

HQ240 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 9: **HQ240 Differential Pin Pair Summary XCV600E, XCV1000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	P92	P93	NA	IO _DLL_L40P
1	5	P89	P87	NA	IO _DLL_L40N
2	1	P210	P209	NA	IO _DLL_L6P
3	0	P213	P215	NA	IO _DLL_L6N
IO LVDS Total Pairs: 64, Asynchronous Output Pairs: 53					
0	0	P236	P237	NA	VREF
1	0	P234	P235	√	-
2	0	P228	P229	√	VREF
3	0	P223	P224	√	-
4	0	P220	P221	√	-
5	0	P217	P218	√	VREF
6	1	P209	P215	NA	IO_LVDS_DLL
7	1	P205	P206	√	VREF
8	1	P202	P203	√	-
9	1	P199	P200	√	-
10	1	P194	P195	√	VREF
11	1	P191	P192	√	VREF
12	1	P188	P189	√	-
13	1	P186	P187	NA	VREF
14	1	P184	P185	√	CS
15	2	P178	P177	√	DIN, D0

Table 9: **HQ240 Differential Pin Pair Summary XCV600E, XCV1000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	2	P174	P173	√	-
17	2	P171	P170	√	VREF
18	2	P168	P167	√	D1
19	2	P163	P162	√	D2
20	2	P160	P159	√	-
21	2	P157	P156	√	D3
22	2	P155	P154	1	VREF
23	2	P153	P152	√	-
24	3	P145	P144	√	D4, VREF
25	3	P142	P141	√	-
26	3	P139	P138	√	D5
27	3	P134	P133	√	VREF
28	3	P131	P130	√	VREF
29	3	P128	P127	√	-
30	3	P126	P125	1	VREF
31	3	P124	P123	√	INIT
32	4	P118	P117	√	-
33	4	P114	P113	√	-
34	4	P111	P110	√	VREF
35	4	P108	P107	√	VREF
36	4	P103	P102	√	-
37	4	P100	P99	√	-
38	4	P97	P96	√	VREF
39	4	P95	P94	NA	VREF
40	5	P93	P87	NA	IO_LVDS_DLL
41	5	P84	P82	NA	VREF
42	5	P79	P78	√	-
43	5	P74	P73	√	VREF
44	5	P71	P70	√	VREF
45	5	P68	P67	√	-
46	5	P66	P65	NA	VREF
47	5	P64	P63	√	-

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
3	IO_D4_L73P_YY	W4	
3	IO_VREF_L73N_YY	W5	
3	IO_L74P_Y	Y3	
3	IO_L74N_Y	Y4	
3	IO_L75P_Y	AA1	
3	IO_L75N_Y	Y5	
3	IO_L76P_Y	AA3	
3	IO_VREF_L76N_Y	AA4	3
3	IO_L77P_Y	AB3	
3	IO_L77N_Y	AA5	
3	IO_L78P_Y	AC1	
3	IO_L78N_Y	AB4	
3	IO_L79P_YY	AC3	
3	IO_D5_L79N_YY	AB5	
3	IO_D6_L80P_YY	AC4	
3	IO_VREF_L80N_YY	AD3	
3	IO_L81P_Y	AE1	
3	IO_L81N_Y	AC5	
3	IO_L82P_Y	AD4	
3	IO_VREF_L82N_Y	AF1	4
3	IO_L83P_Y	AF2	
3	IO_L83N_Y	AD5	
3	IO_L84P_Y	AG2	
3	IO_VREF_L84N_Y	AE4	1
3	IO_L85P_YY	AH1	
3	IO_VREF_L85N_YY	AE5	
3	IO_L86P_Y	AF4	
3	IO_L86N_Y	AJ1	
3	IO_L87P_Y	AJ2	
3	IO_L87N_Y	AF5	
3	IO_L88P_Y	AG4	
3	IO_VREF_L88N_Y	AK2	
3	IO_L89P_Y	AJ3	
3	IO_L89N_Y	AG5	
3	IO_L90P_Y	AL1	

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
3	IO_VREF_L90N_Y	AH4	3
3	IO_D7_L91P_YY	AJ4	
3	IO_INIT_L91N_YY	AH5	
3	IO	U4	
4	GCK0	AL17	
4	IO	AJ8	
4	IO	AJ11	
4	IO	AK6	
4	IO	AK9	
4	IO_L92P_YY	AL4	
4	IO_L92N_YY	AJ6	
4	IO_L93P_Y	AK5	
4	IO_VREF_L93N_Y	AN3	3
4	IO_L94P_YY	AL5	
4	IO_L94N_YY	AJ7	
4	IO_VREF_L95P_YY	AM4	
4	IO_L95N_YY	AM5	
4	IO_L96P_Y	AK7	
4	IO_L96N_Y	AL6	
4	IO_L97P_YY	AM6	
4	IO_L97N_YY	AN6	
4	IO_VREF_L98P_YY	AL7	
4	IO_L98N_YY	AJ9	
4	IO_L99P_Y	AN7	
4	IO_VREF_L99N_Y	AL8	1
4	IO_L100P_Y	AM8	
4	IO_L100N_Y	AJ10	
4	IO_VREF_L101P_Y	AL9	4
4	IO_L101N_Y	AM9	
4	IO_L102P_Y	AK10	
4	IO_L102N_Y	AN9	
4	IO_VREF_L103P_YY	AL10	
4	IO_L103N_YY	AM10	
4	IO_L104P_YY	AL11	

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
7	IO_L74N_Y	G4
7	IO_VREF_L74P_Y	H3
7	IO_L75N_YY	G2
7	IO_L75P_YY	F5
7	IO_L76N	F4
7	IO_L76P	F1
7	IO_L77N_YY	G3
7	IO_L77P_YY	F2
7	IO_L78N_Y	E1
7	IO_VREF_L78P_Y	D1[1]
7	IO_L79N	E4
7	IO_L79P	E2
7	IO_L80N_Y	F3
7	IO_VREF_L80P_Y	C1
7	IO_L81N_YY	D2
7	IO_L81P_YY	E3
7	IO_VREF_L82N	B1[2]
7	IO_L82P	A2
2	CCLK	D15
3	DONE	R14
NA	DXN	R4
NA	DXP	P4
NA	M0	N3
NA	M1	P2
NA	M2	R3
NA	PROGRAM	P15
NA	TCK	C4
NA	TDI	A15
2	TDO	B14
NA	TMS	D3
NA	VCCINT	C3
NA	VCCINT	C14
NA	VCCINT	D4

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
NA	VCCINT	D13
NA	VCCINT	E5
NA	VCCINT	E12
NA	VCCINT	M5
NA	VCCINT	M12
NA	VCCINT	N4
NA	VCCINT	N13
NA	VCCINT	P3
NA	VCCINT	P14
0	VCCO	F8
0	VCCO	E8
1	VCCO	F9
1	VCCO	E9
2	VCCO	H12
2	VCCO	H11
3	VCCO	J12
3	VCCO	J11
4	VCCO	M9
4	VCCO	L9
5	VCCO	M8
5	VCCO	L8
6	VCCO	J6
6	VCCO	J5
7	VCCO	H6
7	VCCO	H5
NA	GND	T16
NA	GND	T1
NA	GND	R15
NA	GND	R2
NA	GND	L11
NA	GND	L10
NA	GND	L7
NA	GND	L6

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	NC	L2
NA	NC	F6
NA	NC	F25
NA	NC	F21
NA	NC	F2
NA	NC	C26
NA	NC	C25
NA	NC	C2
NA	NC	C1
NA	NC	B6
NA	NC	B26
NA	NC	B24
NA	NC	B21
NA	NC	B16
NA	NC	B11
NA	NC	B1
NA	NC	AF25
NA	NC	AF24
NA	NC	AF2
NA	NC	AE6
NA	NC	AE3
NA	NC	AE26
NA	NC	AE24
NA	NC	AE21
NA	NC	AE16
NA	NC	AE14
NA	NC	AE11
NA	NC	AE1
NA	NC	AD25
NA	NC	AD2
NA	NC	AD1
NA	NC	AA6
NA	NC	AA25
NA	NC	AA21
NA	NC	AA2
NA	NC	A3
NA	NC	A25

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	NC	A2
NA	NC	A15
NA	VCCINT	G7
NA	VCCINT	G20
NA	VCCINT	H8
NA	VCCINT	H19
NA	VCCINT	J9
NA	VCCINT	J10
NA	VCCINT	J11
NA	VCCINT	J16
NA	VCCINT	J17
NA	VCCINT	J18
NA	VCCINT	K9
NA	VCCINT	K18
NA	VCCINT	L9
NA	VCCINT	L18
NA	VCCINT	T9
NA	VCCINT	T18
NA	VCCINT	U9
NA	VCCINT	U18
NA	VCCINT	V9
NA	VCCINT	V10
NA	VCCINT	V11
NA	VCCINT	V16
NA	VCCINT	V17
NA	VCCINT	V18
NA	VCCINT	Y7
NA	VCCINT	Y20
NA	VCCINT	W8
NA	VCCINT	W19
0	VCCO	J13
0	VCCO	J12
0	VCCO	H9
0	VCCO	H12
0	VCCO	H11

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
6	IO_VREF_L245N_Y	AB40[1]
6	IO_L245P_Y	AC39
7	IO	F38
7	IO	H40
7	IO	H41
7	IO	J42
7	IO	K39
7	IO	L42
7	IO	N40
7	IO	T40
7	IO	U40
7	IO	V38
7	IO	W42
7	IO	Y42
7	IO	AA42
7	IO_L246N_YY	AA41
7	IO_L246P_YY	AB39
7	IO_L247N_Y	Y41
7	IO_VREF_L247P_Y	AA39[1]
7	IO_L248N_YY	Y40
7	IO_L248P_YY	Y39
7	IO_L249N_YY	Y38
7	IO_VREF_L249P_YY	W41
7	IO_L250N_Y	W40
7	IO_L250P_Y	W39
7	IO_L251N_Y	W38
7	IO_L251P_Y	V41
7	IO_L252N_YY	V39
7	IO_L252P_YY	V40
7	IO_L253N_YY	V42
7	IO_VREF_L253P_YY	U39
7	IO_L254N_Y	U41
7	IO_L254P_Y	U38
7	IO_L255N_Y	U42
7	IO_L255P_Y	T39
7	IO_L256N_YY	T41

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
7	IO_L256P_YY	T38
7	IO_L257N_Y	R39
7	IO_VREF_L257P_Y	T42
7	IO_L258N_Y	R42
7	IO_L258P_Y	R38
7	IO_L259N	R40
7	IO_L259P	P39
7	IO_L260N_Y	R41
7	IO_L260P_Y	P38
7	IO_L261N_Y	P42
7	IO_L261P_Y	N39
7	IO_L262N_Y	P40
7	IO_L262P_Y	M39
7	IO_L263N_YY	P41
7	IO_L263P_YY	M38
7	IO_L264N_YY	N42
7	IO_VREF_L264P_YY	L39
7	IO_L265N_Y	L38
7	IO_L265P_Y	N41
7	IO_L266N_YY	K40
7	IO_L266P_YY	M42
7	IO_L267N_YY	M40
7	IO_VREF_L267P_YY	K38
7	IO_L268N_Y	M41
7	IO_L268P_Y	J40
7	IO_L269N_Y	J39
7	IO_VREF_L269P_Y	L40
7	IO_L270N_YY	J38
7	IO_L270P_YY	L41
7	IO_L271N_YY	K42
7	IO_VREF_L271P_YY	H39
7	IO_L272N_Y	K41
7	IO_L272P_Y	H38
7	IO_L273N_Y	J41
7	IO_L273P_Y	G40
7	IO_L274N_YY	H42
7	IO_L274P_YY	G39

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
3	IO_L127P_YY	Y24
3	IO_VREF_L127N_YY	AB28
3	IO_L128P_YY	AC30
3	IO_L128N_YY	AA25
3	IO_L129P	W21
3	IO_L129N	AA24
3	IO_L130P_YY	AB26
3	IO_L130N_YY	AD30
3	IO_L131P_YY	Y22
3	IO_VREF_L131N_YY	AC27
3	IO_L132P	AD28
3	IO_L132N	AB25
3	IO_L133P_YY	AC26
3	IO_L133N_YY	AE30
3	IO_L134P_YY	AD27
3	IO_L134N_YY	AF30
3	IO_L135P	AF29
3	IO_VREF_L135N	AB24
3	IO_L136P_YY	AB23
3	IO_L136N_YY	AE28
3	IO_L137P_Y	AG30[3]
3	IO_L137N_Y	AC25[4]
3	IO_L138P_YY	AE26
3	IO_VREF_L138N_YY	AG29[1]
3	IO_L139P	AH30
3	IO_L139N	AC24
3	IO_L140P	AF28[3]
3	IO_L140N	AD25[4]
3	IO_D7_L141P_YY	AH29
3	IO_INIT_L141N_YY	AA22
4	GCK0	AJ16
4	IO	AB19[4]
4	IO	AC16[4]
4	IO	AC19
4	IO	AD18[4]
4	IO	AD21[4]

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
4	IO	AE15[4]
4	IO	AE18[4]
4	IO	AE21
4	IO	AE24[5]
4	IO	AF17[5]
4	IO	AF18[5]
4	IO	AJ18[4]
4	IO	AK18
4	IO	AK25[5]
4	IO	AK27[4]
4	IO	AH23[4]
4	IO	AH24[5]
4	IO_L142P_YY	AF27
4	IO_L142N_YY	AK28
4	IO_L143P_YY	AG26[4]
4	IO_L143N_YY	AH27[3]
4	IO_L144P	AD23
4	IO_L144N	AJ27
4	IO_VREF_L145P	AB21[1]
4	IO_L145N	AF25
4	IO_L146P	AC22[4]
4	IO_L146N	AH26[4]
4	IO_L147P_YY	AA21
4	IO_L147N_YY	AG25
4	IO_VREF_L148P_YY	AJ26
4	IO_L148N_YY	AD22
4	IO_L149P	AA20
4	IO_L149N	AH25
4	IO_L150P	AC21
4	IO_L150N	AF24
4	IO_L151P_YY	AG24
4	IO_L151N_YY	AK26
4	IO_VREF_L152P_YY	AJ24
4	IO_L152N_YY	AF23
4	IO_L153P	AE23
4	IO_L153N	AB20
4	IO_L154P	AC20

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	3	AA30	W24	4	-
121	3	AA29	V20	1	-
122	3	Y27	W23	NA	-
123	3	Y26	AB30	√	D5
124	3	V21	AA28	√	VREF
125	3	Y25	AA27	4	-
126	3	W22	Y23	4	-
127	3	Y24	AB28	4	VREF
128	3	AC30	AA25	√	-
129	3	W21	AA24	2	-
130	3	AB26	AD30	√	-
131	3	Y22	AC27	√	VREF
132	3	AD28	AB25	2	-
133	3	AC26	AE30	4	-
134	3	AD27	AF30	√	-
135	3	AF29	AB24	1	VREF
136	3	AB23	AE28	4	-
137	3	AG30	AC25	3	-
138	3	AE26	AG29	4	VREF
139	3	AH30	AC24	1	-
140	3	AF28	AD25	NA	-
141	3	AH29	AA22	√	INIT
142	4	AF27	AK28	√	-
143	4	AG26	AH27	4	-
144	4	AD23	AJ27	2	-
145	4	AB21	AF25	2	VREF
146	4	AC22	AH26	2	-
147	4	AA21	AG25	√	-
148	4	AJ26	AD22	√	VREF
149	4	AA20	AH25	1	-
150	4	AC21	AF24	1	-
151	4	AG24	AK26	√	-
152	4	AJ24	AF23	√	VREF
153	4	AE23	AB20	2	-

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	4	AC20	AG23	2	-
155	4	AF22	AE22	√	-
156	4	AJ22	AG22	√	VREF
157	4	AK24	AD20	NA	-
158	4	AA19	AF21	4	-
159	4	AH22	AA18	NA	VREF
160	4	AG21	AK23	NA	-
161	4	AH21	AD19	4	-
162	4	AE20	AJ21	2	-
163	4	AG20	AF20	2	-
164	4	AC18	AF19	2	-
165	4	AJ20	AE19	√	-
166	4	AK22	AH20	√	VREF
167	4	AG19	AB17	1	-
168	4	AJ19	AD17	1	-
169	4	AA16	AA17	√	-
170	4	AK21	AB16	√	VREF
171	4	AG18	AK20	2	-
172	4	AK19	AD16	2	-
173	4	AE16	AE17	√	-
174	4	AG17	AJ17	√	VREF
175	4	AD15	AH17	NA	-
176	4	AG16	AK17	4	VREF
177	5	AF16	AH16	NA	IO_ LVDS_DLL
178	5	AC15	AG15	4	VREF
179	5	AB15	AF15	√	-
180	5	AA15	AF14	√	VREF
181	5	AH15	AK15	√	-
182	5	AB14	AF13	2	-
183	5	AH14	AJ14	2	-
184	5	AE14	AG13	√	VREF
185	5	AK13	AD13	√	-
186	5	AE13	AF12	1	-
187	5	AC13	AA13	1	-

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
3	IO_L153P_YY	AD31
3	IO_VREF_L153N_YY	AF33
3	IO_L154P_Y	AC28
3	IO_L154N_Y	AF31
3	IO_L155P_Y	AC27[5]
3	IO_L155N_Y	AF32[4]
3	IO_L156P_Y	AE29
3	IO_VREF_L156N_Y	AD28[2]
3	IO_L157P_YY	AD30
3	IO_L157N_YY	AG32
3	IO_L158P_YY	AC26[5]
3	IO_L158N_YY	AH33[4]
3	IO_L159P_YY	AD26
3	IO_VREF_L159N_YY	AF30
3	IO_L160P_Y	AC25
3	IO_L160N_Y	AH32
3	IO_L161P_Y	AE28[5]
3	IO_L161N_Y	AL34[4]
3	IO_L162P_Y	AG30
3	IO_L162N_Y	AD27
3	IO_L163P_YY	AF29
3	IO_L163N_YY	AK34
3	IO_L164P_YY	AD25[5]
3	IO_L164N_YY	AE27[4]
3	IO_L165P_Y	AJ33
3	IO_VREF_L165N_Y	AH31
3	IO_L166P_Y	AE26
3	IO_L166N_Y	AL33
3	IO_L167P	AF28
3	IO_L167N	AL32
3	IO_L168P_Y	AJ31
3	IO_VREF_L168N_Y	AF27
3	IO_L169P_Y	AG29
3	IO_L169N_Y	AJ32

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
3	IO_L170P_Y	AK33
3	IO_L170N_Y	AH30
3	IO_D7_L171P_YY	AK32
3	IO_INIT_L171N_YY	AK31
3	IO	V34
4	GCK0	AH18
4	IO	AE21[3]
4	IO	AG18
4	IO	AG23
4	IO	AH24[3]
4	IO	AH25[3]
4	IO	AJ28[3]
4	IO	AK18[3]
4	IO	AK19[3]
4	IO	AL25
4	IO	AL27[3]
4	IO	AL30[3]
4	IO	AN18
4	IO	AN22[3]
4	IO	AN24[3]
4	IO_L172P_YY	AP31
4	IO_L172N_YY	AK29
4	IO_L173P_Y	AP30
4	IO_L173N_Y	AN31
4	IO_L174P_Y	AH27
4	IO_L174N_Y	AN30
4	IO_VREF_L175P_Y	AM30
4	IO_L175N_Y	AK28
4	IO_L176P_Y	AG26
4	IO_L176N_Y	AN29
4	IO_L177P_YY	AF25
4	IO_L177N_YY	AM29
4	IO_VREF_L178P_YY	AL29

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	VCCO_2	T23
NA	VCCO_2	T24
NA	VCCO_2	R23
NA	VCCO_2	R24
NA	VCCO_2	P23
NA	VCCO_2	P24
NA	VCCO_2	P32
NA	VCCO_2	N23
NA	VCCO_3	V23
NA	VCCO_3	V24
NA	VCCO_3	Y23
NA	VCCO_3	Y24
NA	VCCO_3	W23
NA	VCCO_3	W24
NA	VCCO_3	AJ34
NA	VCCO_3	AE30
NA	VCCO_3	AC24
NA	VCCO_3	AB23
NA	VCCO_3	AB24
NA	VCCO_3	AA23
NA	VCCO_3	AA24
NA	VCCO_3	AA32
NA	VCCO_4	AD18
NA	VCCO_4	AC18
NA	VCCO_4	AC19
NA	VCCO_4	AC20
NA	VCCO_4	AC21
NA	VCCO_4	AC22
NA	VCCO_4	AP29
NA	VCCO_4	AM21
NA	VCCO_4	AK25
NA	VCCO_4	AD19
NA	VCCO_4	AD20
NA	VCCO_4	AD21

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	VCCO_4	AD22
NA	VCCO_4	AD23
NA	VCCO_5	AC17
NA	VCCO_5	AD17
NA	VCCO_5	AC13
NA	VCCO_5	AC14
NA	VCCO_5	AC15
NA	VCCO_5	AC16
NA	VCCO_5	AP6
NA	VCCO_5	AM14
NA	VCCO_5	AK10
NA	VCCO_5	AD12
NA	VCCO_5	AD13
NA	VCCO_5	AD14
NA	VCCO_5	AD15
NA	VCCO_5	AD16
NA	VCCO_6	V11
NA	VCCO_6	V12
NA	VCCO_6	Y11
NA	VCCO_6	Y12
NA	VCCO_6	W11
NA	VCCO_6	W12
NA	VCCO_6	AJ1
NA	VCCO_6	AE5
NA	VCCO_6	AC11
NA	VCCO_6	AB11
NA	VCCO_6	AB12
NA	VCCO_6	AA3
NA	VCCO_6	AA11
NA	VCCO_6	AA12
NA	VCCO_7	U11
NA	VCCO_7	U12
NA	VCCO_7	N12
NA	VCCO_7	M11

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T_{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V_{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	• Numerous minor edits. • Data sheet upgraded to Preliminary. • Preview -8 numbers added to **Virtex-E Electrical Characteristics** tables.
8/1/00	1.6	• Reformatted entire document to follow new style guidelines. • Changed speed grade values in tables on pages 35-37.
9/20/00	1.7	• Min values added to **Virtex-E Electrical Characteristics** tables. • XCV2600E and XCV3200E numbers added to **Virtex-E Electrical Characteristics** tables (Module 3). • Corrected user I/O count for XCV100E device in Table 1 (Module 1). • Changed several pins to “No Connect in the XCV100E“ and removed duplicate V_{CCINT} pins in Table ~ (Module 4). • Changed pin J10 to “No connect in XCV600E” in Table 74 (Module 4). • Changed pin J30 to “V_{REF} or I/O option only in the XCV600E” in Table 74 (Module 4). • Corrected pair 18 in Table 75 (Module 4) to be “AO in the XCV1000E, XCV1600E“.
11/20/00	1.8	• Upgraded speed grade -8 numbers in **Virtex-E Electrical Characteristics** tables to Preliminary. • Updated minimums in Table 13 and added notes to Table 14. • Added to note 2 to **Absolute Maximum Ratings**. • Changed speed grade -8 numbers for $T_{SHCKO32}$, T_{REG}, T_{BCCS}, and T_{ICKOF}. • Changed all minimum hold times to –0.4 under **Global Clock Set-Up and Hold for LVTTL Standard, with DLL**. • Revised maximum T_{DLLPW} in -6 speed grade for **DLL Timing Parameters**. • Changed GCLK0 to BA22 for FG860 package in Table 46.
2/12/01	1.9	• Revised footnote for Table 14. • Added numbers to **Virtex-E Electrical Characteristics** tables for XCV1000E and XCV2000E devices. • Updated Table 27 and Table 78 to include values for XCV400E and XCV600E devices. • Revised Table 62 to include pinout information for the XCV400E and XCV600E devices in the BG560 package. • Updated footnotes 1 and 2 for Table 76 to include XCV2600E and XCV3200E devices.